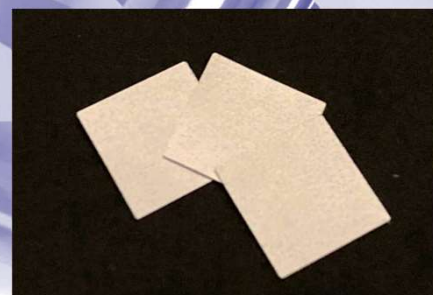


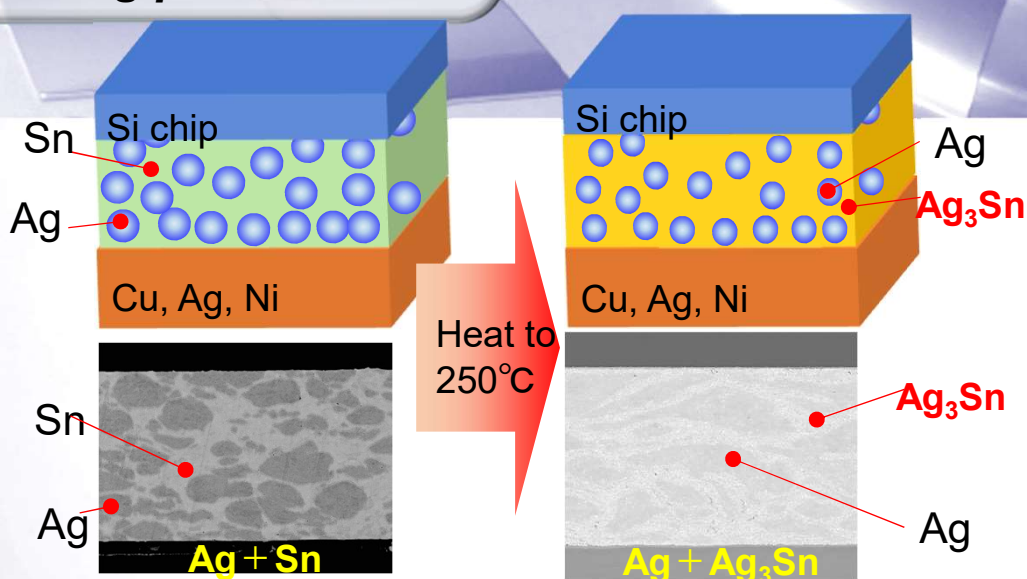
AgSn TLP (Transient Liquid Phase diffusion bonding) Sheet

Applications

- ✓ Die bonding of power devices
- ✓ Thermal interface material (TIM)



Bonding process



Features

- ✓ High bonding strength



Share strength
20~50 MPa

- ✓ Environmentally friendly



Pb free
Organic free

- ✓ High thermal durability
Shear strength 20~50 MPa
(300 deg.C)
Thermal cycle test
over 3,000 cyc.
(-50↔200 deg.C)



- ✓ Large-area bonding is available
Max. 20 mm × 20 mm



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